

LTM4633 144LD 15mm X 15mm X 5.01mm (TABLE OF MATERIAL DECLARATION)

The LTM4633 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2959	Barium Compounds	7727-43-7	0.00589	1.99
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.07786	26.31
				Copper Metal	7440-50-8	0.13313	44.99
				Copper Compounds	147-14-8	0.00005	0.02
				Ecotoxic substances	7440-38-2 7440-28-0	0.00002	0.01
				Gold metal or alloy	7440-57-5	0.00047	0.16
				Nickel	7440-02-0	0.00367	1.24
				Zinc	7440-66-6	0.00025	0.08
				Continuous Filament Fiber Glass	65997-17-3	0.06120	20.68
				Acrylic Resin	non-disclosure	0.01122	3.79
				Expoxy Resin	non-disclosure	0.00016	0.05
				Chromium (III) oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00027	0.09
				Talcinot containing fibers like asbestos	14807-96-6	0.00068	0.23
				Arcomatic carbonyl compounds	non-disclosure	0.00065	0.22
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium Caobonate	471-34-1	0.00003	0.01
				Amine compounds	non-disclosure	0.00009	0.03
				Leveling agent and others	non-disclosure	0.00027	0.09
				2	Solder Paste	Alloy	0.0170
Sb	7440-36-0	0.00085	5.00				
3	Passive/Active Components		0.8321	Iron Powder (Fe)	7439-89-6	0.63213	75.97
				Copper (Cu)	7440-50-8	0.16330	19.62
				Nickel (Ni)	7440-02-0	0.00444	0.53
				Tin (Sn)	7440-31-5	0.00593	0.71
				Ceramic (Ba) Compounds	12047-27-7	0.02632	3.16
4	PMU24-QFN		0.10420				
	Chip			Silicon	7440-21-3	0.00725	6.96
	Die Attach			Phenolic resin	54208-63-8	0.00021	0.20
				Silver	7440-22-4	0.00117	1.12
	Encapsulation			Carbon Black	1333-86-4	0.00045	0.43
				Epoxy Resin	29690-82-2	0.00449	4.31
				Silica	60676-86-0	0.03997	38.36
				Copper	7440-50-8	0.04580	43.95
	Lead Frame			Iron	7439-89-6	0.00113	1.08
				Phosphorus	7723-14-0	0.00002	0.02
				Zinc	7440-66-6	0.00006	0.06
				Gold	7440-57-5	0.00001	0.01
	Terminal Finish			Nickel	7440-02-0	0.00091	0.87
				Palladium	7440-05-3	0.00009	0.09
				Copper	7440-50-8	0.00264	2.53
	Wirebond						

5	HeatSink	Copper	0.4267	Copper	7440-50-8	0.42665	100.00
6	Active lcs	Silicon	0.0019	Silicon	7440-21-3	0.00185	100.00
7	Wire	Gold	0.0017	Au	7440-57-5	0.00170	99.99
8	Epoxy		0.0013	Silver Bisphenol A diglycidyl ether polymer	7440-22-4	0.00044	34.06
				Phenol polymer with formaldehyde glycidyl ether	25085-99-88	0.00014	10.97
				Phonel-formaldehyde polymer	28064-14-4	0.00027	20.69
				Epicglorohyryn-4 4-isopropylldene diphenol resin	9003-38-6	0.00002	1.72
				Amine adduct	non-disclosure	0.00013	9.72
				2,3-Epoxypropyl neodecanoate	26761-45-5	0.00013	9.72
				Treated fumed silica	67762-90-7	0.00004	3.39
9	Solder Ball	SAC305	0.2436	Sn	-	0.23508	96.50
				Ag	-	0.00731	3.00
				Cu	-	0.00122	0.50
10	Encapsulation	Epoxy Resin	1.3253	Fused Silica	60676-86-0	1.02315	77.20
				Epoxy Resin	-	0.11795	8.90
				Phenol Resin	-	0.11795	8.90
				Crytalline Silica	14808-60-7	0.03976	3.00
				Carbon Black	1333-86-4	0.00663	0.50
				Metal Hydroxide	-	0.01988	1.50
Total Package Weight			3.2497				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts